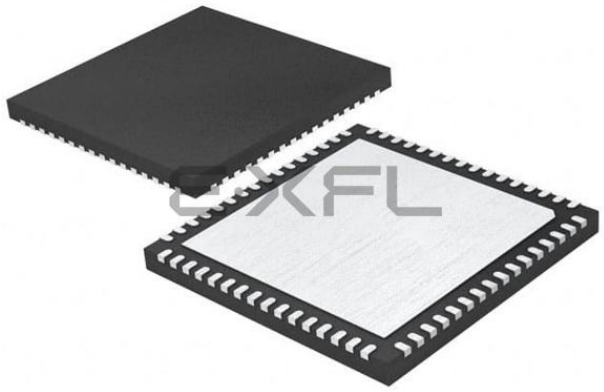
Microchip Technology - DSPIC33FJ64MC506A-H/MR Datasheet



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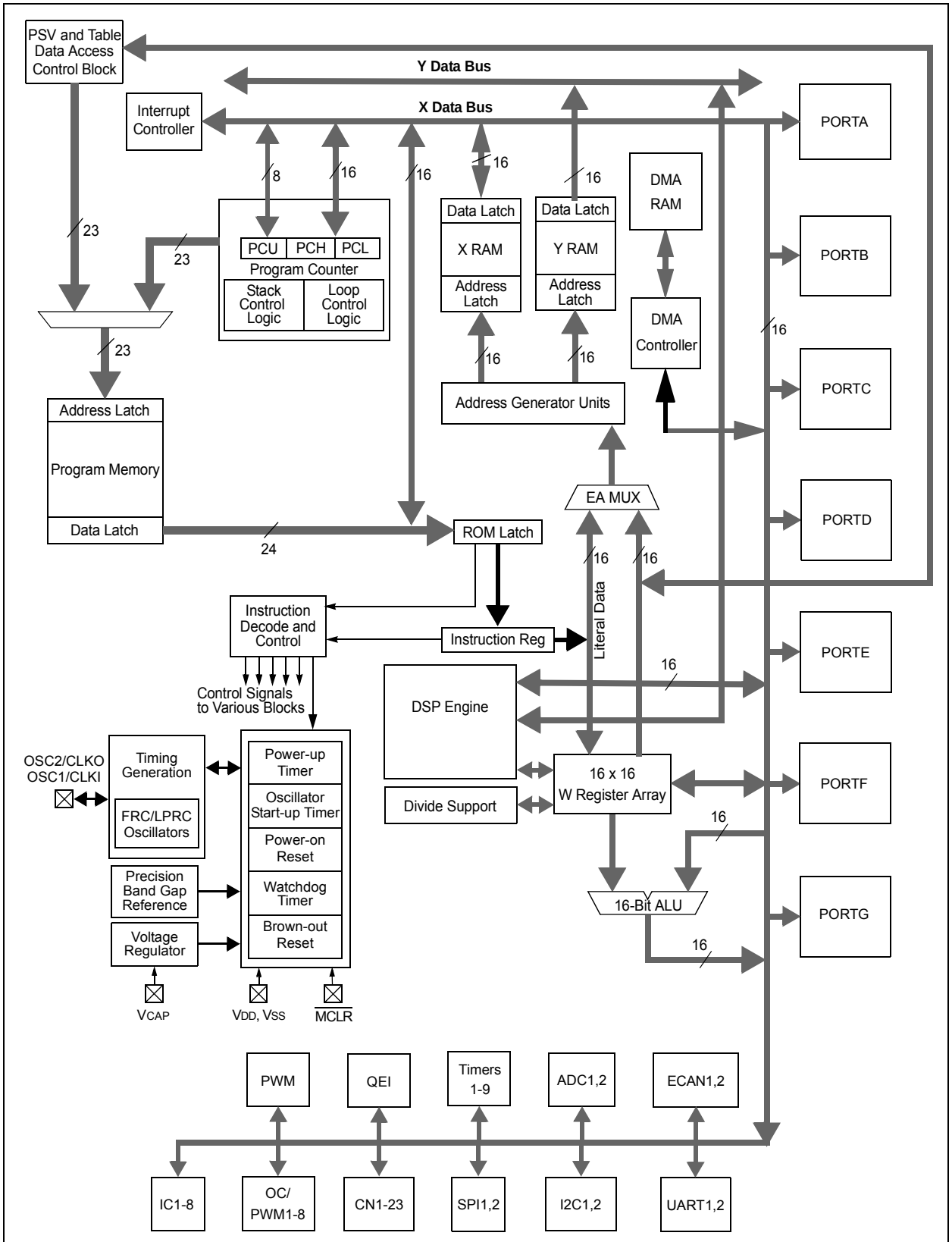
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	20 MIPS
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64mc506a-h-mr

FIGURE 1-1: dsPIC33FJXXXMCX06A/X08A/X10A GENERAL BLOCK DIAGRAM



Note: Not all pins or features are implemented on all device pinout configurations. See pinout diagrams for the specific pins and features present on each device.

3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33FJXXXMCX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 2. "CPU"** (DS70204) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJXXXMCX06A/X08A/X10A CPU module has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for DSP. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space. The actual amount of program memory implemented varies by device. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

The dsPIC33FJXXXMCX06A/X08A/X10A devices have sixteen, 16-bit working registers in the programmer's model. Each of the working registers can serve as a data, address or address offset register. The 16th working register (W15) operates as a software Stack Pointer (SP) for interrupts and calls.

The dsPIC33FJXXXMCX06A/X08A/X10A instruction set has two classes of instructions: MCU and DSP. These two instruction classes are seamlessly integrated into a single CPU. The instruction set includes many addressing modes and is designed for optimum 'C' compiler efficiency. For most instructions, the dsPIC33FJXXXMCX06A/X08A/X10A devices are capable of executing a data (or program data) memory read, a working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing A + B = C operations to be executed in a single cycle.

A block diagram of the CPU is shown in Figure 3-1 and the programmer's model for the dsPIC33FJXXXMCX06A/X08A/X10A is shown in Figure 3-2.

3.1 Data Addressing Overview

The data space can be addressed as 32K words or 64 Kbytes, and is split into two blocks referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear data space. Certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y data space boundary is device-specific.

Overhead-free circular buffers (Modulo Addressing mode) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. Furthermore, the X AGU circular addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data reordering for radix-2 FFT algorithms.

The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K program word boundary defined by the 8-bit Program Space Visibility Page register (PSVPAG). The program to data space mapping feature lets any instruction access program space as if it were data space.

The data space also includes 2 Kbytes of DMA RAM, which is primarily used for DMA data transfers but may be used as general purpose RAM.

3.2 DSP Engine Overview

The DSP engine features a high-speed, 17-bit by 17-bit multiplier, a 40-bit ALU, two 40-bit saturating accumulators and a 40-bit bidirectional barrel shifter. The barrel shifter is capable of shifting a 40-bit value up to 16 bits right or left in a single cycle. The DSP instructions operate seamlessly with all other instructions and have been designed for optimal real-time performance. The `MAC` instruction and other associated instructions can concurrently fetch two data operands from memory while multiplying two W registers, and accumulating and optionally saturating the result in the same cycle. This instruction functionality requires that the RAM memory data space be split for these instructions and linear for all others. Data space partitioning is achieved in a transparent and flexible manner through dedicating certain working registers to each address space.

4.2 Data Address Space

The dsPIC33FJXXXMCX06A/X08A/X10A CPU has a separate 16-bit wide data memory space. The data space is accessed using separate Address Generation Units (AGUs) for read and write operations. Data memory maps of devices with different RAM sizes are shown in Figure 4-3 through Figure 4-5.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the data space. This arrangement gives a data space address range of 64 Kbytes or 32K words. The lower half of the data memory space (that is, when EA<15> = 0) is used for implemented memory addresses, while the upper half (EA<15> = 1) is reserved for the Program Space Visibility area (see **Section 4.6.3 "Reading Data from Program Memory Using Program Space Visibility"**).

dsPIC33FJXXXMCX06A/X08A/X10A devices implement a total of up to 30 Kbytes of data memory. Should an EA point to a location outside of this area, an all-zero word or byte will be returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all data space EAs resolve to bytes. The Least Significant Bytes of each word have even addresses, while the Most Significant Bytes have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® microcontrollers and improve data space memory usage efficiency, the dsPIC33FJXXXMCX06A/X08A/X10A instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word that contains the byte, using the LSb of any EA to determine which byte to select. The selected byte is placed onto the LSb of the data path. That is, data memory and registers are organized as two parallel, byte-wide entities with shared (word) address decode but separate write lines. Data byte writes only write to the corresponding side of the array or register which matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction underway is completed; if it occurred on a write, the instruction will be executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the Least Significant Byte. The Most Significant Byte is not modified.

A sign-extend instruction (SE) is provided to allow users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, users can clear the MSb of any W register by executing a zero-extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0x0000 to 0x07FF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33FJXXXMCX06A/X08A/X10A core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note:	The actual set of peripheral features and interrupts varies by the device. Please refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area between 0x0000 and 0x1FFF is referred to as the Near Data Space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. Additionally, the whole data space is addressable using MOV instructions, which support Memory Direct Addressing mode with a 16-bit address field, or by using Indirect Addressing mode using a working register as an Address Pointer.

TABLE 4-10: QEI REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
QEI1CON	01E0	CNTERR	—	QEISIDL	INDX	UPDN	QEIM<2:0>			SWPAB	PCDOUT	TQGATE	TQCKPS<1:0>		POSRES	TQCS	UPDN_SRC	0000 0000 0000 0000
DFLT1CON	01E2	—	—	—	—	—	IMV<1:0>		CEID	QEOUT	QECK<2:0>			—	—	—	—	0000 0000 0000 0000
POS1CNT	01E4	Position Counter<15:0>																0000 0000 0000 0000
MAX1CNT	01E6	Maximum Count<15:0>																1111 1111 1111 1111

Legend: u = uninitialized bit, — = unimplemented, read as '0'

TABLE 4-11: I2C1 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C1RCV	0200	—	—	—	—	—	—	—	—	I2C1 Receive Register								0000
I2C1TRN	0202	—	—	—	—	—	—	—	—	I2C1 Transmit Register								00FF
I2C1BRG	0204	—	—	—	—	—	—	—	Baud Rate Generator Register									0000
I2C1CON	0206	I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C1STAT	0208	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
I2C1ADD	020A	—	—	—	—	—	—	I2C1 Address Register										0000
I2C1MSK	020C	—	—	—	—	—	—	I2C1 Address Mask Register										0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-12: I2C2 REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C2RCV	0210	—	—	—	—	—	—	—	—	I2C2 Receive Register								0000
I2C2TRN	0212	—	—	—	—	—	—	—	—	I2C2 Transmit Register								00FF
I2C2BRG	0214	—	—	—	—	—	—	—	Baud Rate Generator Register									0000
I2C2CON	0216	I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C2STAT	0218	ACKSTAT	TRSTAT	—	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
I2C2ADD	021A	—	—	—	—	—	—	I2C2 Address Register										0000
I2C2MSK	021C	—	—	—	—	—	—	I2C2 Address Mask Register										0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-22: ECAN1 REGISTER MAP WHEN WIN (C1CTRL<0>) = 1

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0400-041E	See definition when WIN = x																
C1BUFPNT1	0420	F3BP<3:0>				F2BP<3:0>				F1BP<3:0>				F0BP<3:0>				0000
C1BUFPNT2	0422	F7BP<3:0>				F6BP<3:0>				F5BP<3:0>				F4BP<3:0>				0000
C1BUFPNT3	0424	F11BP<3:0>				F10BP<3:0>				F9BP<3:0>				F8BP<3:0>				0000
C1BUFPNT4	0426	F15BP<3:0>				F14BP<3:0>				F13BP<3:0>				F12BP<3:0>				0000
C1RXM0SID	0430	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM0EID	0432	EID<15:8>								EID<7:0>								xxxx
C1RXM1SID	0434	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM1EID	0436	EID<15:8>								EID<7:0>								xxxx
C1RXM2SID	0438	SID<10:3>								SID<2:0>			—	MIDE	—	EID<17:16>		xxxx
C1RXM2EID	043A	EID<15:8>								EID<7:0>								xxxx
C1RXF0SID	0440	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF0EID	0442	EID<15:8>								EID<7:0>								xxxx
C1RXF1SID	0444	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF1EID	0446	EID<15:8>								EID<7:0>								xxxx
C1RXF2SID	0448	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF2EID	044A	EID<15:8>								EID<7:0>								xxxx
C1RXF3SID	044C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF3EID	044E	EID<15:8>								EID<7:0>								xxxx
C1RXF4SID	0450	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF4EID	0452	EID<15:8>								EID<7:0>								xxxx
C1RXF5SID	0454	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF5EID	0456	EID<15:8>								EID<7:0>								xxxx
C1RXF6SID	0458	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF6EID	045A	EID<15:8>								EID<7:0>								xxxx
C1RXF7SID	045C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF7EID	045E	EID<15:8>								EID<7:0>								xxxx
C1RXF8SID	0460	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF8EID	0462	EID<15:8>								EID<7:0>								xxxx
C1RXF9SID	0464	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF9EID	0466	EID<15:8>								EID<7:0>								xxxx
C1RXF10SID	0468	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF10EID	046A	EID<15:8>								EID<7:0>								xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

6.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) have a relatively long start-up time. Therefore, one or more of the following conditions is possible after SYSRST is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

6.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it begins to monitor the system clock source when SYSRST is released. If a valid clock source is not available at this time, the device automatically switches to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine.

6.2.2.1 FSCM Delay for Crystal and PLL Clock Sources

When the system clock source is provided by a crystal oscillator and/or the PLL, a small delay, TFSCM, is automatically inserted after the POR and PWRT delay times. The FSCM does not begin to monitor the system clock source until this delay expires. The FSCM delay time is nominally 500 μs and provides additional time for the oscillator and/or PLL to stabilize. In most cases, the FSCM delay prevents an oscillator failure trap at a device Reset when the PWRT is disabled.

6.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset, with the exception of two registers. The Reset value for the Reset Control register, RCON, depends on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, depends on the type of Reset and the programmed values of the oscillator Configuration bits in the FOSC Configuration register.

REGISTER 7-10: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0 (CONTINUED)

bit 2 **OC1IE:** Output Compare Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 1 **IC1IE:** Input Capture Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 0 **INT0IE:** External Interrupt 0 Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	U = Unimplemented bit, read as '0'		
R = Readable bit	W = Writable bit	HS = Hardware Settable bit	HC = Hardware Clearable bit
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit
1 = Enables the I2Cx module and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module. All I^2C™ pins are controlled by port functions.

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters an Idle mode
0 = Continue module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I^2C slave)
1 = Release SCLx clock
0 = Hold SCLx clock low (clock stretch)
If STREN = 1:
Bit is R/W (i.e., software may write '0' to initiate stretch and write '1' to release clock). Hardware clear at beginning of slave transmission. Hardware clear at end of slave reception.
If STREN = 0:
Bit is R/S (i.e., software may only write '1' to release clock). Hardware clear at beginning of slave transmission.

bit 11 **IPMIEN:** Intelligent Peripheral Management Interface (IPMI) Enable bit
1 = IPMI mode is enabled; all addresses Acknowledged
0 = IPMI mode disabled

bit 10 **A10M:** 10-Bit Slave Address bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit
1 = Slew rate control disabled
0 = Slew rate control enabled

bit 8 **SMEN:** SMBus Input Levels bit
1 = Enable I/O pin thresholds compliant with SMBus specification
0 = Disable SMBus input thresholds

bit 7 **GCEN:** General Call Enable bit (when operating as I^2C slave)
1 = Enable interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)
0 = General call address disabled

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^2C slave)
Used in conjunction with the SCLREL bit.
1 = Enable software or receive clock stretching
0 = Disable software or receive clock stretching

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 5 **ACKDT:** Acknowledge Data bit (when operating as I^2C master, applicable during master receive)
Value that will be transmitted when the software initiates an Acknowledge sequence.
1 = Send NACK during Acknowledge
0 = Send ACK during Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit
(when operating as I^2C master, applicable during master receive)
1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit. Hardware clear at end of master Acknowledge sequence
0 = Acknowledge sequence not in progress

bit 3 **RCEN:** Receive Enable bit (when operating as I^2C master)
1 = Enables Receive mode for I^2C. Hardware clear at end of eighth bit of master receive data byte
0 = Receive sequence not in progress

bit 2 **PEN:** Stop Condition Enable bit (when operating as I^2C master)
1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence
0 = Stop condition not in progress

bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I^2C master)
1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence
0 = Repeated Start condition not in progress

bit 0 **SEN:** Start Condition Enable bit (when operating as I^2C master)
1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence
0 = Start condition not in progress

REGISTER 22-1: ADxCON1: ADCx CONTROL REGISTER 1 (where x = 1 or 2) (CONTINUED)

bit 3 **SIMSAM:** Simultaneous Sample Select bit (only applicable when CHPS<1:0> = 01 or 1x)
When AD12B = 1, SIMSAM is: U-0, Unimplemented, Read as '0'.
1 = Samples CH0, CH1, CH2, CH3 simultaneously (when CHPS<1:0> = 1x); or samples CH0 and CH1 simultaneously (when CHPS<1:0> = 01)
0 = Samples multiple channels individually in sequence

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion. SAMP bit is auto-set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit
1 = ADC sample/hold amplifiers are sampling
0 = ADC sample/hold amplifiers are holding
If ASAM = 0, software may write '1' to begin sampling. Automatically set by hardware if ASAM = 1.
If SSRC = 000, software may write '0' to end sampling and start conversion. If SSRC ≠ 000, automatically cleared by hardware to end sampling and start conversion.

bit 0 **DONE:** ADC Conversion Status bit
1 = ADC conversion cycle is completed
0 = ADC conversion not started or in progress
Automatically set by hardware when ADC conversion is complete. Software may write '0' to clear DONE status (software not allowed to write '1'). Clearing this bit will NOT affect any operation in progress. Automatically cleared by hardware at start of a new conversion.

REGISTER 22-6: ADxCHS0: ADCx INPUT CHANNEL 0 SELECT REGISTER

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NB	—	—	CH0SB<4:0>				
bit 15							bit 8

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA	—	—	CH0SA<4:0>(1)				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CH0NB:** Channel 0 Negative Input Select for Sample B bit
Same definition as bit 7.

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **CH0SB<4:0>:** Channel 0 Positive Input Select for Sample B bits
Same definition as bit<4:0>.

bit 7 **CH0NA:** Channel 0 Negative Input Select for Sample A bit
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREF-

bit 6-5 **Unimplemented:** Read as '0'

bit 4-0 **CH0SA<4:0>:** Channel 0 Positive Input Select for Sample A bits(1)
11111 = Channel 0 positive input is AN31
11110 = Channel 0 positive input is AN30
•
•
•
00010 = Channel 0 positive input is AN2
00001 = Channel 0 positive input is AN1
00000 = Channel 0 positive input is AN0

Note 1: ADC2 can only select AN0-AN15 as positive inputs.

REGISTER 22-9: ADxPCFGH: ADCx PORT CONFIGURATION REGISTER HIGH(1,2,3,4)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PCFG31	PCFG30	PCFG29	PCFG28	PCFG27	PCFG26	PCFG25	PCFG24
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PCFG23	PCFG22	PCFG21	PCFG20	PCFG19	PCFG18	PCFG17	PCFG16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PCFG<31:16>:** ADC Port Configuration Control bits

1 = Port pin in Digital mode; port read input enabled; ADC input multiplexer connected to AVSS

0 = Port pin in Analog mode; port read input disabled; ADC samples pin voltage

Note 1: On devices without 32 analog inputs, all PCFG bits are R/W by user. However, PCFG bits are ignored on ports without a corresponding input on the device.

2: ADC2 only supports analog inputs, AN0-AN15; therefore, no ADC2 port Configuration register exists.

3: PCFGx = ANx, where x = 16 through 31.

4: The PCFGx bits have no effect if the ADC module is disabled by setting the ADxMD bit in the PMDx register. In this case, all port pins multiplexed with ANx will be in Digital mode.

REGISTER 22-10: ADxPCFGL: ADCx PORT CONFIGURATION REGISTER LOW(1,2,3,4)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PCFG15	PCFG14	PCFG13	PCFG12	PCFG11	PCFG10	PCFG9	PCFG8
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PCFG7	PCFG6	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PCFG<15:0>:** ADC Port Configuration Control bits

1 = Port pin in Digital mode; port read input enabled; ADC input multiplexer connected to AVSS

0 = Port pin in Analog mode; port read input disabled; ADC samples pin voltage

Note 1: On devices without 16 analog inputs, all PCFG bits are R/W by user. However, PCFG bits are ignored on ports without a corresponding input on the device.

2: On devices with two analog-to-digital modules, both AD1PCFGL and AD2PCFGL will affect the configuration of port pins multiplexed with AN0-AN15.

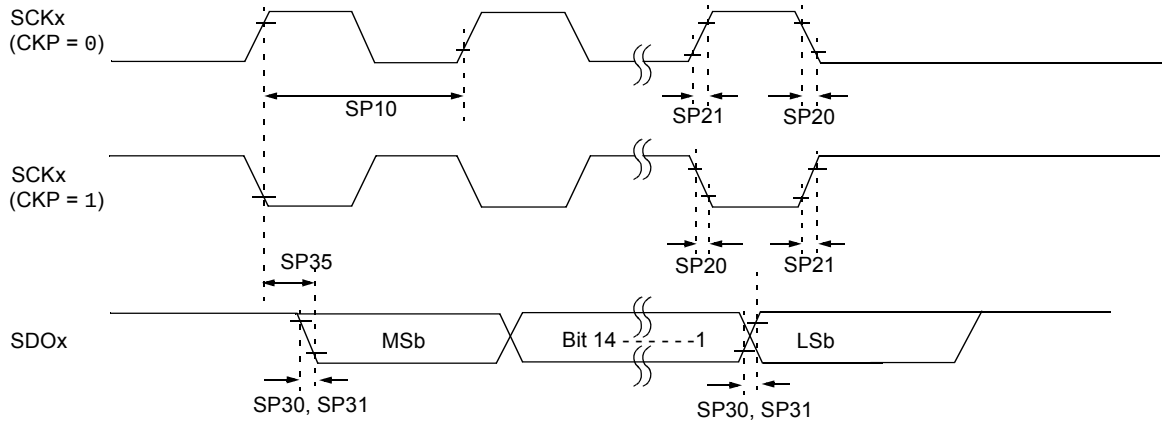
3: PCFGx = ANx, where x = 0 through 15.

4: The PCFGx bits have no effect if the ADC module is disabled by setting the ADxMD bit in the PMDx register. In this case, all port pins multiplexed with ANx will be in Digital mode.

TABLE 26-32: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY

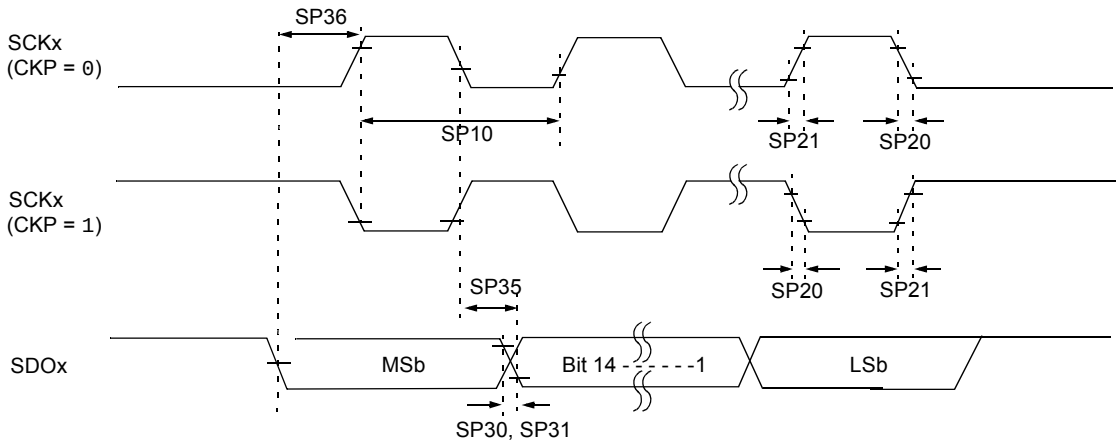
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 26-33	—	—	0,1	0,1	0,1
10 MHz	—	Table 26-34	—	1	0,1	1
10 MHz	—	Table 26-35	—	0	0,1	1
15 MHz	—	—	Table 26-36	1	0	0
11 MHz	—	—	Table 26-37	1	1	0
15 MHz	—	—	Table 26-38	0	1	0
11 MHz	—	—	Table 26-39	0	0	0

FIGURE 26-14: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-15: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-33: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCK Frequency	—	—	15	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-18: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

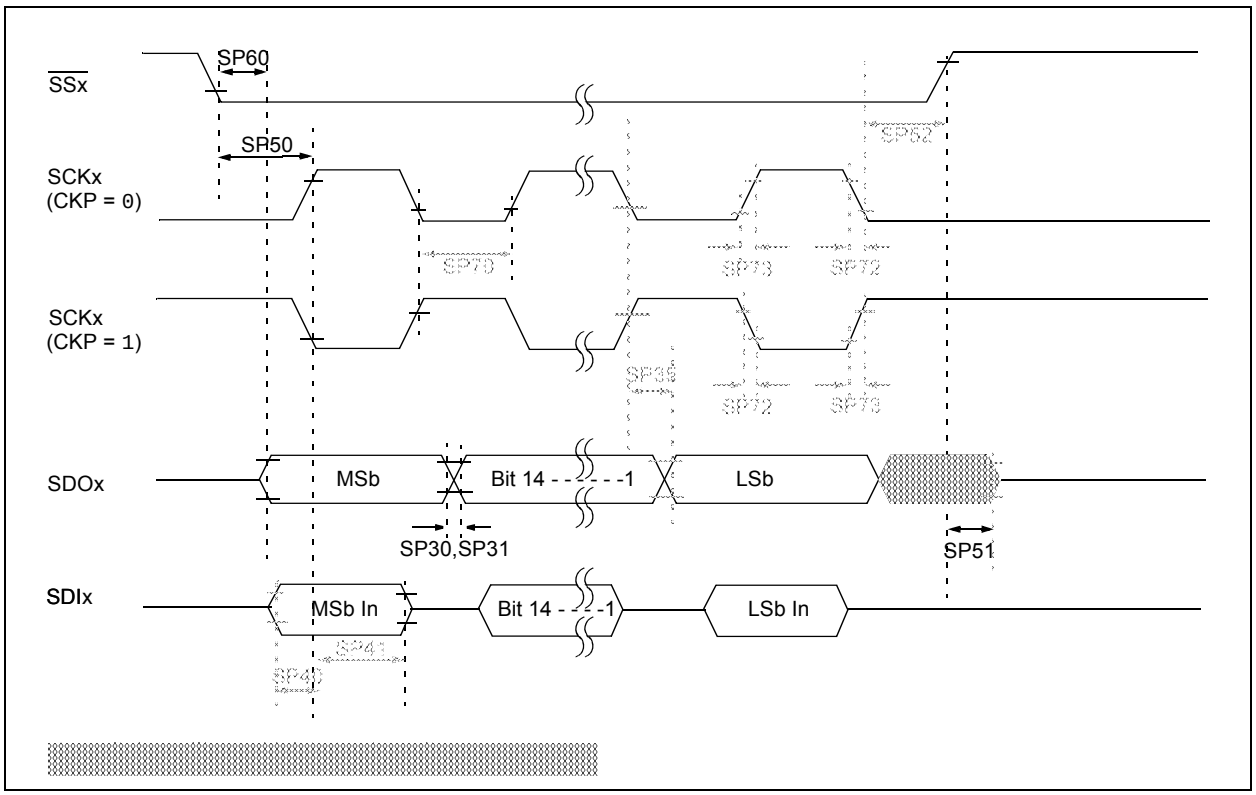


TABLE 27-6: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

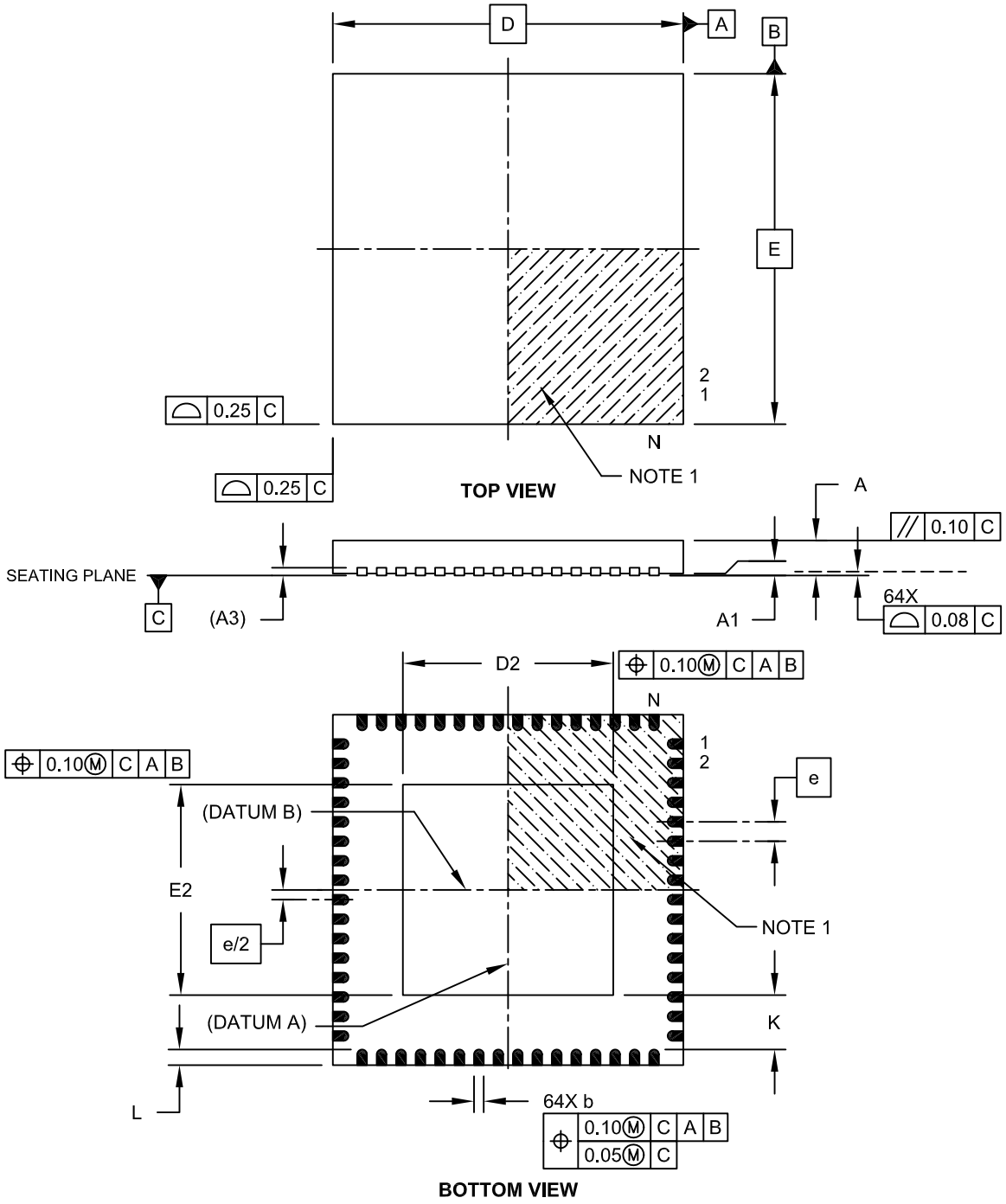
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for High Temperature				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
HDO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤ 1.8 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	—	—	0.4	V	IOL ≤ 3.6 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V See **Note 1**
HDO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -1.8 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V See **Note 1**
HDO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -1.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -1.85 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -1.4 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO, RC15	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

29.2 Package Details

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body with 5.40 x 5.40 Exposed Pad [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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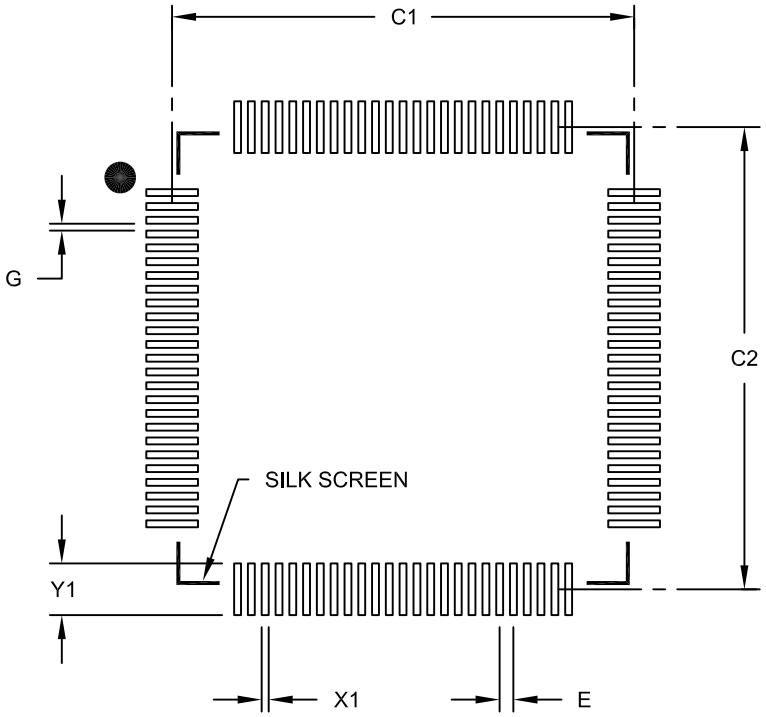
100-Lead Plastic Thin Quad Flatpack (PT)- 12x12x1mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Contact Pad Spacing	C1		13.40	
Contact Pad Spacing	C2		13.40	
Contact Pad Width (X100)	X1			0.20
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100B

Revision C (March 2011)

This revision includes typographical and formatting changes throughout the data sheet text. In addition, all instances of VDDCORE have been removed.

All other major changes are referenced by their respective section in the following table.

TABLE B-2: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Updated the title of **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**. The frequency limitation for device PLL start-up conditions was updated in **Section 2.7 "Oscillator Value Conditions on Device Start-up"**. The second paragraph in **Section 2.9 "Unused I/Os"** was updated.
Section 4.0 "Memory Organization"	The All Resets values for the following SFRs in the Timer Register Map were changed (see Table 4-6): • TMR1 • TMR2 • TMR3 • TMR4 • TMR5 • TMR6 • TMR7 • TMR8 • TMR9
Section 9.0 "Oscillator Configuration"	Added Note 3 to the OSCCON: Oscillator Control Register (see Register 9-1). Added Note 2 to the CLKDIV: Clock Divisor Register (see Register 9-2). Added Note 1 to the PLLFBD: PLL Feedback Divisor Register (see Register 9-3). Added Note 2 to the OSCTUN: FRC Oscillator Tuning Register (see Register 9-4).
Section 22.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the VREFL references in the ADC1 module block diagram (see Figure 22-1).
Section 23.0 "Special Features"	Added a new paragraph and removed the third paragraph in **Section 23.1 "Configuration Bits"**. Added the column "RTSP Effects" to the Configuration Bits Descriptions (see Table 23-2).

NOTES: